## **DES Machine**

### Hyper Etching

UCE is devoted to innovating cutting edge technology of PCB wet-processing equipment to meet the requirements of industry development.



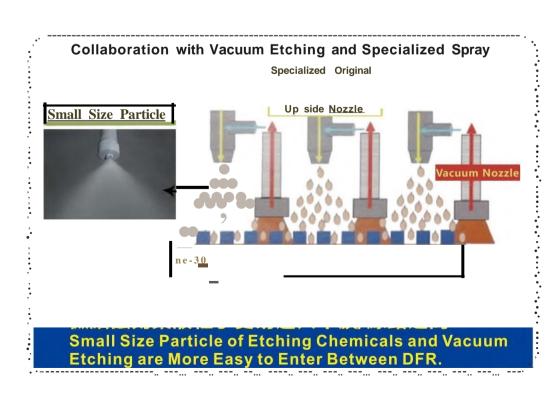
### **Capability**

Panel Size(FPC):	500mmWxSOOmm L(max) 250mmWx250mm L(min) 0.025mm(core) +12/12μm Cu~1.2mm
Panel Size (Rigid Board):	630mmWx 630mm1(max) 355mmWx 355mm1(min) 0.025mm(core) +12/12µm Cu~3.2mm
Panel Size (Back Panel):	1OSOmmWx 11 OOmmL(max) 355mmWx 355mml(min) 0.5~12mm

Specification and capability are subject to contract, and machine should work with proper chemicals.

#### **Hyper Etching Advantages**

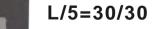
- 1. Suitable for fine line circuit
- 2. Suitable for thick copper etching
- 3. Enhance etching factor





#### L/5=30/30

12μm Cu, 10μm DFR DFR L/S=40/20 After Etching---> 30/30 E/F=S.0~6.0



18μm Cu, 15μm DFR DFR L/S=40/20 After Etching---> 30/30 E/F=4.0~4.5





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